

REMARKS

Claim Rejections 35 U.S.C. § 112, first paragraph

The Examiner has rejected claim 9 under 35 U.S.C. § 112, first paragraph, as failing to comply with the written description requirement.

Applicant respectfully disagrees with the Examiner. Support is provided at paragraphs [0013] and [0017].

One of ordinary skill in the art of processing semiconductors at the time the invention was made would understand that during polishing in a slurry (150), a front surface of a polishing pad (120) would contact a front surface of a wafer (160). Consequently, a cathode (130) would contact a rear surface of the polishing pad (120) in an embodiment of Applicant's claimed invention. Furthermore, an anode (170) would contact a rear surface of the wafer (160) in an embodiment of Applicant's claimed invention. See Figure 1.

Thus, claim 9 contains subject matter which was described in the specification in such a way as to reasonably convey to one skilled in the relevant art that the inventor possessed the claimed invention at the time the application was filed.

In view of the foregoing, Applicant respectfully requests the Examiner to withdraw the rejections to claim 9 under 35 U.S.C. § 112, first paragraph.

Claim Rejections 35 U.S.C. § 103 (a)

The Examiner has rejected claims 9, 10, and 16-28 under 35 U.S.C. § 103 (a) as being unpatentable over Uzoh et al. (US 5,807,165).

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Applicant respectfully disagrees with the Examiner. Applicant has amended claim 9. Support is provided in paragraph [0022] on pages 7-8 and paragraph [0012] on page 5 in the specification.

Claim 9, as amended, of Applicant's claimed invention claims an apparatus (100) including: a platen (110); a polishing pad (120) located over the platen, the polishing pad having properties that may be changed by a power supply to optimize polish rate and polish selectivity for different materials, the properties including: hardness, stiffness, porosity, abrasiveness, and absorbance; a segmented cathode located between the platen and the polishing pad; a slurry (150) located on the polishing pad; a wafer (160) located on the polishing pad and the slurry; a wafer carrier (180) to hold the wafer; a segmented anode located between the wafer and the wafer carrier; the power supply (190) to apply a voltage between the segmented cathode and the segmented anode; and a computer (200), the computer to vary the voltage. See Figure 1.

In contrast, the Uzoh et al. reference cited by the Examiner teaches an apparatus (60) including a rotatable workpiece carrier (66), a plurality of workpiece electrodes (67) disposed in a recess R of the carrier, a rotatable platen (62) attached to a rotatable shaft (68), a platen electrode (63) attached to the platen, a polishing pad (64) mounted on the platen, a means for urging the carrier against the pad, a slurry supply system in fluid communication with the pad, and a source (80) to vary magnitude and polarity of current as a function of time. See Figures 7-10 and 14. Also, see Col. 5, lines 44-51 and lines 10-22.

However, Uzoh et al. does not teach an apparatus including: a polishing pad having properties that may be changed by a power supply to optimize polish rate and polish selectivity for different materials where the properties include: hardness, stiffness, porosity, abrasiveness, and absorbance.

Thus, Uzoh et al. does not teach, suggest, or render obvious Applicant's invention, as claimed in claim 9.

Consequently, Applicant's claimed invention, as claimed in claim 9, would not have been obvious to one of ordinary skill in the art of processing semiconductors at the time the invention was made.

Claims 10 and 16-28 are dependent on claim 9, as amended, and, thus, would also not have been obvious to one of ordinary skill in the art of processing semiconductors at the time the invention was made.

In view of the foregoing, Applicant respectfully requests the Examiner to withdraw the rejections to claims 9-10 and 16-28 under 35 U.S.C. § 103(a).

Applicant believes that all claims pending, including amended claim 9, are now in condition for allowance so such action is earnestly solicited at the earliest possible date.

Pursuant to 37 C.F.R. § 1.136 (a) (3), Applicant hereby requests and authorizes the U.S. Patent and Trademark Office to treat any concurrent or future reply that requires a petition for extension of time as incorporating a petition for extension of time for the appropriate length of time.

Should there be any additional charge or fee, including extension of time fees and fees under 37 C.F.R. § 1.16 and § 1.17, please charge Deposit Account No. 02-2666.

If a telephone interview would in any way expedite the prosecution of this application, the Examiner is invited to contact the undersigned at (408) 720-8300.

Respectfully submitted,

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Dated: ____/September 21/____, 2006 ____/George Chen/_____

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